Quiz 1, Time for quiz: max1 hour Allowed help: Std. mathematical and physica The evaluation will be a service only	l tables, calculator, no internet, no textbook.
1. I'm really looking forward to take this test $[x]$ (cross mark the politically corre	ct alternative)
Cross mark only the correct course code which you register for [ ] FYS4310 [ ] FYS9310, 3 Cross mark the correct statement(s) only.	
In a CVD reactor for Si epitaxial growth the feed gas is SiCl <sub>2</sub> H <sub>2</sub> and H <sub>2</sub> . The fee The HCl gas concentration in the chamber is proportional to Reaction SiCl <sub>2</sub> H <sub>2</sub>	
$\begin{bmatrix} \mathbf{SiCl_2H_2} \end{bmatrix}$ $\mathbf{[X]}  \mathbf{[SiCl_2H_2]}^{\frac{1}{2}}$	$\frac{\left[\operatorname{SiCl}_{2}\operatorname{H}_{2}\right]\cdot\left[\operatorname{H}_{2}\right]}{\left[\operatorname{HCl}\right]^{2}\left[\operatorname{SiH}_{4}\right]} = K(T) \Rightarrow \left[\operatorname{HCl}\right] \propto \left[\operatorname{SiCl}_{2}\operatorname{H}_{2}\right]^{1/2}$
[] $[SiCl_2H_2]^{0.05}$ [] $[H_2]^4$	
[ ] $\left[\operatorname{SiCl}_{2}\operatorname{H}_{2}\right]^{2}$	
Cross mark the correct statement(s) only  'The energy required to create a Si vacancy (free energy of creation with a net pot that required to to create a neutral one' This statement is  [] Never correct for Si	
<ul> <li>Cross mark the correct statement(s) only</li> <li>The thermal oxidation growth rate for SiO<sub>2</sub> on Si</li> <li>[x] is faster for wet oxidation than for dry oxidation because the equilibrium contain that of oxygen at identical gas pressure. <i>In lecture notes we have said</i> in [some of the content of</li></ul>	ts like this, Other reasons have been given

6 (* 2210 stuff)	
The figure to the right shows a CV curve of a MOS capacitor (Metal-Oxide-Semiconductor). The sign of the voltage is defined as positive when the metal is a positive electrostatic potential with respect to the semiconductor. The graph tell if the semiconductor is n-type or p-type.	c f
The doping type of the semiconductor is .  [x] n-type accumulation at positive bias, attract electrons  [ ] p-type  [ ] don't know	
7 From a CV curves MOS capacitor structures yielding C-V curves like that shown in problem 6  [ ] The dielectric constant of Si NB it say Si, not SiO2,	can be used to find.

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When growing CVD Si at high temperature, the rate limiting mechanism in the growth process is.

[ ] The break down voltage of the oxide no, however you will be unable to measure C when reach BV

[ ] Step creation

[ ] Step flow velocity

[ ] Chemical reaction rate

[ ] The elementary charge

[ ] Space charge neutrality

[x] Gas transport

[ ] Space charge neutrality

[ ] Recombination

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Describe Henry's law in the space provided before problem 10

[x] The area density of charges in the oxide from the flat band

Concentration of gas molecules just inside the surface of a material is proportional to the partial pressure just outside the surface

10
Consider MBE growth of GaAs. Mark the correct statements only.
[ ] The growth is typically performed at atmospheric pressure <i>No</i> , <i>usually UHV</i>
[ ] The growth rate (at constant temperature) varies parabolic with time
[x] The As vapor pressure is much higher than that of Ga
[ ] Crystals can be grown fast, but the quality can not be as good as Czochralski grown (bulk) material
[x] Surface diffusion of ad atoms occur at the growth temperature.
[ ] AlAs is grown in a different growth chamber than where GaAs is grown <i>Usually the same</i> , but of course can be grown in different
[ ] MBE is presently the only technique used for growing Mo(molybdenum) doped GaAs. No Mo doping, Vapor pressure Mo very low,
11
What are the dominant diffusing species during so-called wet oxidation of Si.
[x] water
[ ] silicon
[ ] oxygen
[ ] nitrogen
[ ] vacancies
[ ] hydrogen and oxygen molecules
12
There are many acronyms used throughout the course. Please write the what the following acronyms stands for
[a] VLSI=Very Large Scale Integration
[b] MOS = Metal Oxide Semiconductor
[c] CVD = Chemical Vapor Deposition
[d] MBE = Molecular Beam Epitaxy
[e] LPCVD = Low Pressure Chemical Vapor Deposition (NOT Liquid Phase:-)
[f] ALE = Atomic Layer Epitaxy
[g] SLS = Strained Layer Superlattice

Give an order of magnitude answer to these questions [a] In 1 cm³ of GaAs there are 5Exx atoms where xx = 22 [b] To grow a 1 µm thick oxide on Si in steam at 1000 °C, we need to grow 1Exx sec, where xx = 03 [c] The activation energy for vacancy concentration in Si is 2Exx eV where xx = 0 and where the value for the different charge states adds a spread about 1Eyy eV where yy = 01 [d] The solid solubility of As in Si at 1100 °C is about 1Exx cm³ where xx = 20 [e] The bandgap of InAs is about 3Exx eV where xx = -1
The growth of an epitaxial Si layer in a CVD chamber is diffusion limited, then the instant growth rate dx/dt varies with time as {where k is a parameter independent of t, and x is the thickness)  [ ] k*t [ ] ln(k*t) [ ] exp(-k*t) [x] k [ ] k*t 1/2
The segregation coefficient is important for Czochralski growth because  [ ] The sign indicates whether striations will develop  [x] It explains why floatzone technique yields less oxygen  [ ] It controls nucleation of precipitates in the crystal towards the seed  [ ] It is zero

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The following statements can be true or false. Check with a cross the statements that are TRUE only	
[x] This is a test	
[x] The most common material for the crucible in Czochralskii growth of Si is silica	
[ ] Crystalline Si is too brittle to withstand the processing and handling used for making	
electronic devices	
[ ] A getter process is done during float Zone growth to get as few vacancies as possible in Si	
[x] Twins often occur when growing epitaxial Si on wafers with the surface normal along <111>	
[ ] When silicon is exposed to water vapor at 1000 °C, the surface will be covered by silicon monoxide	
[x] * In silicon the electron mobility in n-type is higher than the hole mobility when the doping concentration	ion
is the same in n and p type.	
[x] In a piece of crystalline Si the room temperature electron mobility is higher than that of the hole in the same material, at all doping concentrations in the range 1E11 cm <sup>3</sup> to 1E20 cm <sup>3</sup> .	
[ ] Vacancies can condense on an atomic plane in a disk like fashion, creating a stacking fault.	
The dislocation bounding that stacking fault is called an extrinsic dislocation it is called intrinsic	
[x] The equilibrium vacancy concentration in Si, depends upon the doping concentration	
[ ] The vacancy concentration in Si decreases with increasing temperature as $1/T$ .	
[ ] It is fundamentally impossible to grow a dislocation free crystal at a finite temperature	
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Which of these denote a polar surface?	
A cold surface	
A surface which is biased	
A surface which is biased positively	
[ ] The surface facing the gas flow in Atomic Layer Deposition	
[x] A AlAs (111) surface	

